

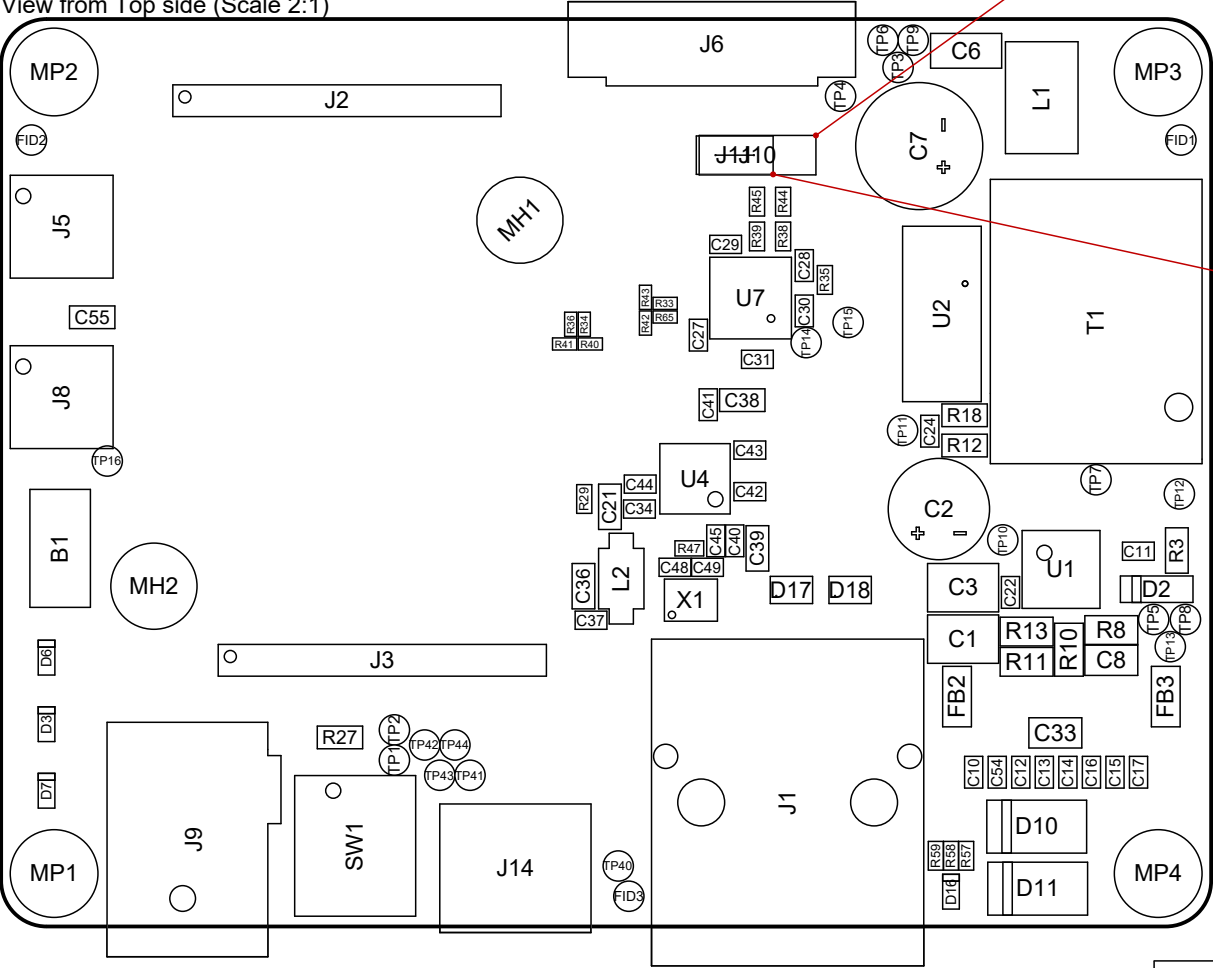
ASSEMBLY NOTES:

Assembly shall conform to IPC-A-610 Class 2.  
Assembly shall conform with RoHS Directive 2011/65/EU.  
Components shall be placed according to the associated CPL and BOM documents.  
Lead-free SAC305 solder shall be used.  
Reflow profile shall comply with J-STD-20C Lead-Free Reflow Profile.  
BGA components shall be 100% checked with x-ray for solder bridges after reflow.  
Finished assemblies shall be removed from panel prior to delivery.

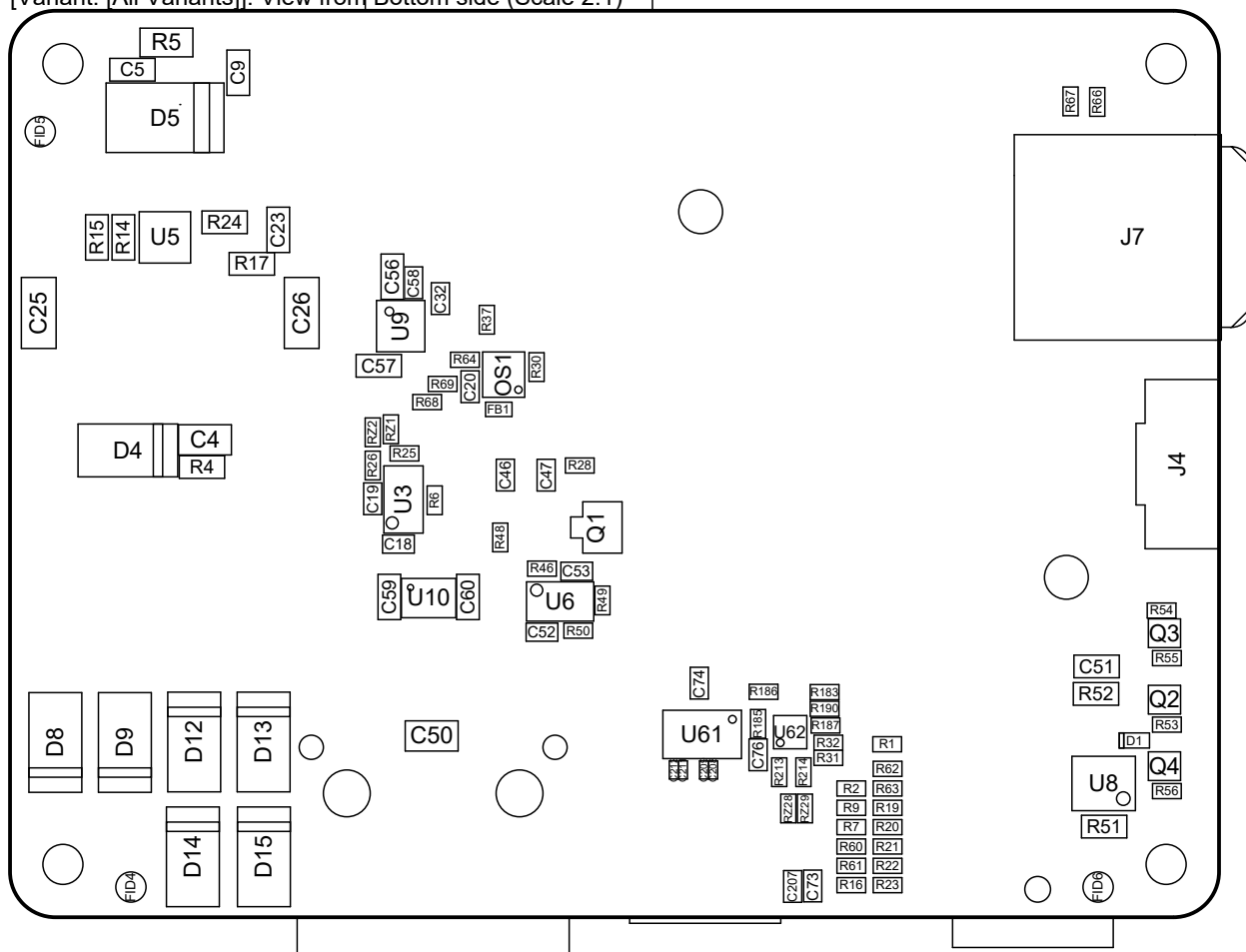
Notes:

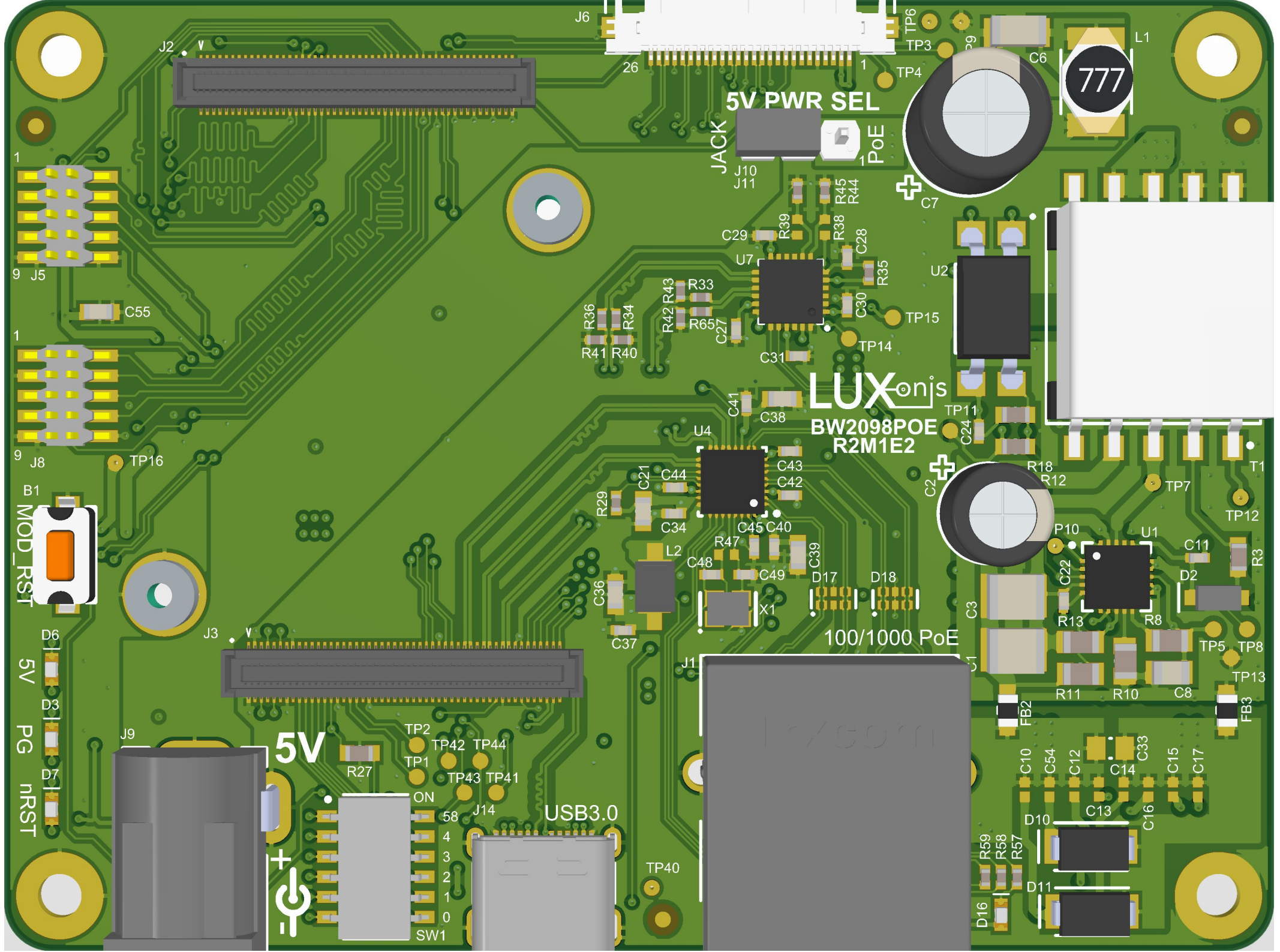
- 1
- J10 is 3 pin header
- 2
- J11 is header jumper, to be placed on J10, pins 2,3.

View from Top side (Scale 2:1)



[Variant: [All Variants]]: View from Bottom side (Scale 2:1)





J2

J6

TP6

L1

5V PWR SEL

JACK

PoE

777

1

9 J5

C55

1

9 J8

TP16

B1

MOD\_RST

D6

5V

D3

PG

nRST

D7

J9

5V



TP2

TP42

TP44

TP1

TP43

TP41

ON

58

J14

USB3.0

4

3

2

1

0

SW1

TP40

10/100m

LUXonjs  
BW2098POE  
R2M1E2

100/1000 PoE



LUXonjs

BW2098POE  
R2M1E2

### J5 Header

MOD_nRST	I2C3_SCL
AUX_IO_IRQ	I2C3_SDA
2485_PGOOD	UART_RX
NC	UART_TX
GND	GND

### J8 Header

SPI_SCK	SPI_SIO0
GND	SPI_SIO1
SPI_SS_0	SPI_SIO2
GPIO6	SPI_SIO3
GND	GND

SDIO

MODULE\_JTAG

